



Mail Stop: AMENDMENT  
PATENT  
8007-1093

IN THE U.S. PATENT AND TRADEMARK OFFICE

In re application of

Kiyohito HIROMITSU et al.

Conf. 2651

Application No. 10/537,358

Group 1796

Filed June 3, 2005

Examiner G. Webb

MOLD CLEANING MATERIAL AND MOLD CLEANING  
METHOD

RESPONSE UNDER 37 C.F.R. § 1.111

Assistant Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

July 24, 2008

Sir:

In response to the non-final Office Action dated March  
24, 2008, Applicants herein provide the following remarks.

**Remarks** begin on page 2 of this paper.

An **Appendix** is attached following the signature page of  
this paper.